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(54) **Programmable logic device**

Programmierbare logische Vorrichtung

Dispositif logique programmable

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## Description

The present invention relates generally to integrated circuits, and more specifically to an electrically erasable programmable read only memory circuit.

Electrically erasable programmable read only memory (EEPROM) finds a wide variety of uses in the electronics industry. They can be used as stand alone memories, such as used with microcomputer systems and controllers. EEPROM memory may also be embedded into various types of user programmable devices, many of which are referred to generally as field programmable logic devices.

EEPROM memory cells can be used in some types of programmable logic devices to store configuration information for such devices. They are also used to define switch connections in a AND-OR array, such as used in programmable logic arrays and more sophisticated devices which are programmed in a similar way.

EEPROM cells, each containing a memory bit, are programmed ON using a high voltage signal to inject charge onto a floating gate. These cells are programmed off by reversing the polarity of the high voltage, and removing charge from the floating gate. Once programmed, the charge on the floating gate causes the floating gate device to behave as a field effect transistor which remains switched either on or off.

The higher voltages needed for programming EEPROM cells require physically larger transistors in other parts of the device which also encounter these higher voltages. These larger devices are necessary in order to avoid hot electron effects and punch through as known in the art. These larger transistors operate at a slower speed than smaller ones, decreasing the overall operating speed of the device.

EP-A-0284724 (Toshiba) is directed to providing a nonvolatile memory device, and in particular to the provision of simple peripheral circuits including the sense amplifier. The document describes a so-called three transistor cell where a floating gate transistor is connected between a write select transistor and a read select transistor. The cell can operate in a data erase mode, data write mode and data read mode according to different voltages applied to the transistors. The read select and write select transistors are of a similar configuration, and thus in particular in the case of the read select transistors present a significant capacitance on the read select lines. The addition of a third transistor as shown in Figures 5 and 7 has as its object to allow a 5V voltage on the read line of the memory cell, instead of 1V previously, without causing a so-called "soft write".

Read/write transistors used to access the floating gate transistors are among those which must be able to handle the higher programming voltages. In addition to their larger size, the circuitry used to drive these transistors must be fabricated using N-channel technology. CMOS circuitry cannot be used to drive the read/write transistors because the higher voltage used therein

makes the drive circuitry more susceptible to latch-up problems. Since N-channel technology is used in the driving circuitry, the maximum signal which can be applied to turn on the read/write transistors during normal operation is  $V_{cc} - V_{Tn}$ . This lower driving voltage provides less signal margin for the read/write transistors, and results in slower operation. Bootstrapping can be used to raise the signal back to  $V_{cc}$ , but the necessary circuitry adds delay.

The design of current EEPROM cells results in undesirable capacitive loads, especially as used in an AND-OR array on a programmable logic device. These capacitive loads increase the switching time of the programmable logic device, reducing its performance.

It would be desirable to provide an EEPROM cell which overcomes many of the important limitations described above. It would be desirable for such a cell to provide improved performance while being compatible with current process technology.

It is therefore an object of the present invention to provide a programmable logic device having an AND-OR array containing an EEPROM cell with improved performance.

According to the present invention there is provided a programmable logic device, having an AND-OR array containing input signal rows and product term signal lines, wherein each junction of a row with a product term signal line contains a switching element, said switching element comprising:

a select transistor having a source/drain terminal connected to a product term signal line and having a control terminal for receiving a select control input on an input signal row;

a floating gate transistor having a source/drain terminal connected to another source/drain terminal of said select transistor, wherein operation of said floating gate transistor is controlled by charge stored on a floating gate through a gate oxide suitable for charge tunnelling, and wherein turning on of said select transistor in response to the select control input causes the product term signal line to indicate the presence or absence of charge on the floating gate whereby the switching element is read; and

a programming transistor having a source/drain terminal connected to another source/drain terminal of said floating gate transistor, having another source/drain terminal connected to a supply voltage, and having a control terminal for receiving a programming control input, wherein charge stored on the floating gate is provided from the supply voltage through said programming transistor; wherein the programming transistor is adapted to receive programming voltages higher than a normal operating voltage and wherein said select transistor is physically smaller than said programming transistor thereby reducing the capacitance presented to the

product term signal line.

The device preferably comprises means for, during a read operation, switching said programming transistor on at all times, connecting the supply voltage to ground, and switching said select transistor on in response to a high voltage applied to its select control input, whereby, when said select transistor is switched on, the product term signal line is connected to ground if said floating gate transistor is controlled to be on by the floating gate, and the product term signal line is not connected to ground through the floating gate transistor otherwise.

The novel features believed characteristic of the invention are set forth in the appended claims. The invention itself however, as well as a preferred mode of use, and further objects and advantages thereof, will best be understood by reference to the following detailed description of an illustrative embodiment when read in conjunction with the accompanying drawings, wherein:

Figure 1 is a schematic diagram of a portion of a known programmable logic device;

Figure 2 is a schematic diagram of an EEPROM cell utilized in the prior art;

Figure 3 is a schematic diagram of a portion of a programmable logic device as known in the prior art;

Figure 4 is a schematic diagram of an improved EEPROM cell according to the present invention; and

Figure 5 is a schematic diagram of a portion of a programmable logic device utilizing the EEPROM cell of the present invention.

Referring to **Figure 1**, a portion of an AND-OR array of a known programmable logic device **10** is shown. Input signal lines **12, 14** carry input signals provided from off chip. Input signal lines **12, 14** are connected to input buffers **16, 18** respectively. Each input buffer **16, 18** provides a true signal line **20, 22** and a complement signal line **24, 26**. Only two input signal lines **12, 14** and input buffers **16, 18** are shown in **Figure 1**, but an actual device typically has a much larger number.

Each of the signal lines **20-26** is connected to a row line **28, 30, 32, 34**. Row lines **28** and **30**, designated with the signals ROW and ROWB carry complementary signals determined by the input on line **12**. Likewise, row lines **32, 34** contain complementary signals determined by the input on line **14**. In addition to input signals, additional row lines can be used to carry feedback signals from output registers (not shown).

A product signal line **36** crosses all of the row lines **28-34**, and drives a sense amplifier **38**. Sense amplifier **38** generates output signal PT. Only one product signal line **36** is shown, but it is understood that many such lines are included in actual devices. A typical device might include, for example, **44** row lines and **122** product signal lines.

As known in the art, the signal available on line **36** is determined by programmed connections made between the row lines **28-34** and the product signal lines **36**. Connections are made at the intersections of these lines by using transistor switches. In field programmable logic devices, a typical transistor switch includes an EEPROM cell which is programmed ON or OFF in order for the connection at any particular point to be made or not made, respectively. EEPROM cells are typically built in pairs, with a single EEPROM cell pair **40, 42** having two switches and being programmed to determine the connections between one product signal line **36** and one row and its complement. In the example above, a device having **44** row lines (22 pairs) and 122 product signal lines would include 2684 EEPROM cell pairs in the AND-OR array.

Referring to **Figure 2**, an EEPROM cell pair **40** as used in the prior art is shown. Floating gate devices **44, 46** are connected to product signal line **36**. Each device contains a floating gate node **48** which is capacitively coupled to a programming voltage supply line **50**. Read/write transistors **52, 54** are connected between floating gate devices **44, 46**, respectively, and product term ground signal line **56**.

During normal operation of the device, signal line **56** is connected to device ground. The signals ROW and ROWB are used to switch read/write transistors **52, 54** respectively. As described above, the signals ROW and ROWB are complementary, so that only one of the read/write transistors **52, 54** is switched on at all times.

As known in the art, the floating gate devices **44, 46** are programmed ON by storing charge on their respective nodes **48**. If floating gate device **44** is programmed ON, and ROW is high, output signal line **36** is connected to ground through floating gate device **44** and transistor **52**. If floating gate device **44** is programmed OFF, device **44** is non-conductive and signal line **36** is not connected to ground. Floating gate device **46** and transistor **54** operate on a similar fashion.

Floating gate device **44** is programmed ON by tunneling charge onto the floating gate node **48** through a thin gate oxide. This is accomplished by driving the signals ROW and PTG to a super voltage while grounding the signal MCGO. The super voltage is substantially higher than the normal operating voltage of the programmable logic device. For example, for a device which normally operates using a supply voltage of 5 volts, the programming super voltage is typically 12-18 volts.

With MCGO at ground, and ROW and PTG at the super voltage, signal line **56** has a net positive charge on it with respect to the floating gate node **48**. Electrons flow from node **48** to signal line **56** through the gate oxide of floating gate device **44** and through transistor **52**. After this tunneling has been completed signal line **50** is connected to ground, leaving a net positive charge on floating gate node **48**. This causes floating gate device **44** to be ON, providing a DC current path between read/

write transistor 52 and output signal line 36.

To program floating gate device 44 OFF, MCGO and ROW are driven to the super voltage and the signal PTG is grounded. This causes the floating gate node 48 to have a net positive charge with respect to signal line 56, causing electrons to tunnel through the gate oxide onto floating gate node 48. When supply line 50 is grounded, a net negative charge is left on the floating gate node 48. This turns floating gate device 44 OFF, providing an open circuit between transistor 52 and signal line 36. During normal operation of the device, both signals MCGO and PTG are grounded.

Figure 3 illustrates a portion of a programmable logic device having a plurality of prior art EEPROM cell pairs 40 connected to a product signal line 36. In the example shown in Figure 3, 22 different true and complement row pairs are connected to each signal line 36.

The floating gate devices 44 and 46 have a relatively large capacitance regardless of whether they are programmed ON or OFF. Since all of the floating gate devices 44, 46 are connected to the product signal line 36, a relatively large lumped capacitance is attached to such signal line 36. As will be appreciated by those skilled in the art, the existence of this capacitance greatly decreases the speed at which the voltage level of line 36 can change. If the combination of floating gate device programming and ROW inputs causes the voltage level on line 36 to change from high to low, or vice versa, the capacitive load provided by the floating gate devices 44, 46 limits the rate of which such change can occur.

The read/write transistors 52, 54 must have a larger than minimum size because of the super voltage signals applied across their source/drains when the gate is low during programming. Larger transistors induce a larger capacitive load than do smaller transistors, which further increases the time required for the signal on output line 36 to change state.

Since the ROW and ROWB signals are driven to a super voltage during programming, additional circuitry must be included to bias the signals during programming. This additional circuitry provides a capacitive load on the lines used to generate ROW and ROWB, thereby decreasing the switching speed of these signals. Since ROW and ROWB must be driven to the super voltage during programming, only N-channel devices can be used in the driving circuitry for these signals. This is necessary in order to prevent a potential latch-up situation which could occur if CMOS devices were used. Since only N-channel devices can be used, the signals ROW and ROWB can never be driven completely to the supply voltage, but instead are limited to  $V_{CC} - V_{Tn}$  unless the signals are bootstrapped. This smaller voltage swing for the signals ROW and ROWB further decreases the switching speed of these signals.

In an AND-OR array, the signals ROW and ROWB are the inverse of each other. Thus, one signal rises when the other signal falls. It is preferable to have both signals change symmetrically in order to ensure equiv-

alent data access times in both directions. In the cell pair 40, if only one of the floating gate devices 44, 46 is programmed ON, there will exist a unidirectional coupling on signal line 36 when the signals ROW and ROWB switch.

This coupling is due to the Miller capacitance created by the gate/drain overlap of the floating gate devices 44, 46 in conjunction with that of devices 52 and 54. For a cell programmed ON, the signal on line 36 will be pulled to a low level through that cell. As ROW rises, charge is coupled onto signal line 36 by the Miller capacitance. This charge must subsequently be removed through the channel of the floating gate device before the signal on line 36 can reach its low level.

The converse occurs when one or more of the ROW floating gate devices 44 are programmed on while all of the ROWB floating gate devices 46 are programmed OFF. When all of the ROW signals are switched off all of the ROWB signals are switched on, and the signal on output line 36 is coupled low from an already low state. Thus, in order to return from a low level on signal line 36 to a high level, signal line 36 must actually recover from an artificially low state below its normal low value.

In both of the situations just described, the extra charge transfer which occurs causes a delay in correctly biasing the signal on line 36. This delay further increases the switching time of the device.

An EEPROM cell pair incorporating two improved cells is shown in Figure 4. Cell pair 60 includes connections to product term output signal line 62 and product term ground 64. These two signal lines 62, 64 function in a manner substantially equivalent to their counterpart signal lines 36 and 56 in the prior art cell pair 40.

Cell pair 60 includes floating gate devices 66 and 68, each of which has a floating gate node 70. The floating gate nodes 70 are capacitively coupled to programming voltage supply line 72, driven by the signal MCGO.

Floating gate devices 66, 68 are connected to the output signal line 62 through select, or read, transistors 74 and 76 respectively. Floating gate devices 66, 68 are connected to the product term ground signal line 64 through decode, or programming, transistors 78 and 80 respectively. Read transistors 74, 76 are driven by the ROW and ROWB signals, respectively, and the programming transistors 78, 80 are driven by the decode signals DECA and DECB, respectively.

The floating gate devices 66, 68 are programmed in a similar fashion to that used for the prior art devices. To program the floating gate devices ON, MCGO is grounded and PTG is driven to the super voltage. For each floating gate device 66, 68 which is to be programmed ON, the corresponding decode signal DECA or DECB, is also driven to the super voltage. This causes tunneling to produce a net positive charge on the floating gate node 70 of the corresponding floating gate device 66 or 68.

In order to program a floating gate device 66 or 68 OFF, MCGO is driven to the super voltage while PTG is

grounded. DECA and DECB are driven to the super voltage for all of the associated floating gate devices **66, 68** which are to be programmed OFF. Tunneling causes a net negative charge to occur on the selected floating gate nodes **70**. During normal operation of the device, both MCGO and PTG are grounded.

During normal operation of the cell pair **60**, both signals DECA and DECB are driven to the positive supply voltage at all times. A depletion-mode N-channel device (not shown) can be used to bring the DECA and DECB signals up to  $V_{cc}$ . Such a device adds some delay to the driving circuitry, but this does not matter since DECA and DECB never change during normal operation of the device. Since only N-channel devices can be used in the driving circuitry for the signals DECA and DECB, the signals will actually have a voltage limited to  $V_{cc}-V_{Tn}$ . This is sufficient to bias programming transistors **78, 80** ON, and has no adverse effect because these transistors are never switched during normal operation.

Since ROW and ROWB are complements, one of the select transistors **74** or **76** will always be ON. If the associated floating gate device **66** or **68** is programmed ON, signal line **62** will be connected to ground. If the associated floating gate device **66, 68** is programmed OFF, signal line **62** will not be connected to ground.

High voltages are applied to the floating gate devices **66, 68** for programming as in the usual case. High voltages are also applied to programming transistors **78, 80**, which must be of a larger size for the reasons described above. The select transistor **74, 76**, which are the ones actually switched during normal operation of the device, are never driven using high programming voltages. Therefore, these devices may be made smaller, resulting in faster switching during normal operation.

Referring to **Figure 5**, a plurality of improved cells **60** are shown connected to an output signal line **62**. Signal line **62** is connected to sense amplifier **82**, which drives the signal PT. The sense amplifier **82** includes a resistive pull-up element (not shown), which pulls the voltage on signal line **62** up to a one level when none of the cell pairs **60** contains a DC path to ground.

It will become apparent from **Figure 5** that only one half of the floating gate devices **66, 68** will be connected to product term signal line **62**. This occurs because only one of the select transistors **74, 76** is on for each row. The select transistors **74, 76** can be designed using minimum channel length devices, since they are not required to handle high voltages during programming. The capacitive load of these transistors **74, 76** is therefore much smaller than that of the floating gate devices **66, 68**. This minimizes the capacitive load on signal line **62**.

Since the ROW and ROWB signals are not driven to the programming super voltage, CMOS circuitry can be used to drive them. This allows the signals ROW and ROWB to actually be driven all the way to the supply voltage. This larger voltage swing than that found in the prior art devices improves their signal margin and allows faster switching times. In addition, there is no high volt-

age driver circuitry connected to the ROW and ROWB signals. This results in a lower capacitance in the driving circuitry, allowing ROW and ROWB to switch faster and contribution to further decreased switching times of the device.

The unidirectional coupling which occurs on signal line **62** in the prior art devices does not occur in the improved EEPROM cell pair **60**. Both of the switching transistors **74** and **76** are connected directly to signal line **62**, and driven by complementary signals ROW and ROWB. When one select transistor switches off, the other switches on. Any charge coupling caused by switching one select transistor is balanced by the switching of the other select transistor in the opposite direction. Thus, a smaller net effect is seen on signal line **62** due to various charge coupling mechanisms.

Although some extra layout area is required for the improved EEPROM cell, a significant speed increase is realized using such improved structure. The area required for the AND-OR array on a programmable logic device is generally not the major portion of the area of the entire device. Thus, a percentage increase for layout area in this region of up to 20% or 25% does not greatly impact the overall area required for fabrication of the device. In return for this small area penalty, significant speed increases are realized for the overall device without requiring a change in fabrication technology.

While the invention has been particularly shown and described with reference to a preferred embodiment, it will be understood by those skilled in the art that various changes in form and detail may be made therein without departing from the scope of the invention as defined by the appended claims.

## Claims

1. A programmable logic device, having an AND-OR array containing input signal rows and product term signal lines, wherein each junction of a row with a product term signal line contains a switching element, said switching element comprising:

a select transistor (**74**) having a source/drain terminal connected to a product term signal line (PT) and having a control terminal for receiving a select control input on an input signal row (ROW);

a floating gate transistor (**66**) having a source/drain terminal connected to another source/drain terminal of said select transistor (**74**), wherein operation of said floating gate transistor (**66**) is controlled by charge stored on a floating gate (**70**) through a gate oxide suitable for charge tunnelling, and wherein turning on of said select transistor (**74**) in response to the select control input (ROW) causes the product term signal line (PT) to indicate the presence

- or absence of charge on the floating gate (70) whereby the switching element is read; and a programming transistor (78) having a source/drain terminal connected to another source/drain terminal of said floating gate transistor (66), having another source/drain terminal connected to a supply voltage (PTG), and having a control terminal for receiving a programming control input (DECA), wherein charge stored on the floating gate (70) is provided from the supply voltage (PTG) through said programming transistor (78); wherein the programming transistor is adapted to receive programming voltages higher than a normal operating voltage and wherein said select transistor (74) is physically smaller than said programming transistor (78) thereby reducing the capacitance presented to the product term signal line (PT).
2. A device according to claim 1, further comprising means for, during a read operation, switching said programming transistor (78) on at all times, connecting the supply voltage (PTG) to ground, and switching said select transistor (74) on in response to a high voltage applied to its select control input (ROW), whereby, when said select transistor (74) is switched on, the product term signal line (PT) is connected to ground if said floating gate transistor (66) is controlled to be on by the floating gate, and the product term signal line (PT) is not connected to ground through the floating gate transistor otherwise.

#### Patentansprüche

1. Programmierbare Logikvorrichtung mit einem UND-ODER-Array, das Eingabesignalreihen und Produktterm-Signalleitungen beinhaltet, bei welcher jede Verbindung einer Reihe mit einer Produktterm-Signalleitung ein Schaltelement beinhaltet, wobei das Schaltelement folgendes aufweist:

einen Auswahltransistor (74) mit einem Source-/Drain-Anschluß, der mit einer Produktterm-Signalleitung (PT) verbunden ist, und mit einem Steueranschluß, um eine Auswahlsteuereingabe auf einer Eingangssignalreihe (ROW) zu empfangen;  
einen Floating-Gate-Transistor (66) mit einem Source-/Drain-Anschluß, der mit einem anderen Source-/Drain-Anschluß des Auswahltransistors (74) verbunden ist, wobei der Betrieb des Floating-Gate-Transistors (66) durch eine Ladung gesteuert wird, die auf einem Floating-Gate (70) durch ein Gateoxid gespeichert ist, das für ein Ladungstunneln geeignet ist, und wobei ein Einschalten des Auswahltransistors

(74) in Antwort auf die Auswahlsteuerungseingabe (ROW) bewirkt, daß die Produktterm-Signalleitung (PT) die Anwesenheit oder Abwesenheit von Ladung auf dem Floating-Gate (70) anzeigt, wodurch das Schaltelement gelesen wird; und

einen Programmiertransistor (78) mit einem Source-/Drain-Anschluß, der mit dem anderen Source-/Drain-Anschluß des Floating-Gate-Transistors (66) verbunden ist, mit einem anderen Source-/Drain-Anschluß, der mit einer Versorgungsspannung (PTG) verbunden ist, und mit einem Steueranschluß zum Empfangen einer Programmier-Steuereingabe (DECA), wobei eine Ladung, die auf dem Floating-Gate (70) gespeichert ist, von der Versorgungsspannung (PTG) durch den Programmiertransistor (78) bereitgestellt wird; wobei der Programmiertransistor angepaßt ist, um Programmiervoltagen zu empfangen, die höher sind als eine normale Betriebsspannung, und wobei der Auswahltransistor (74) physikalisch kleiner ist als der Programmiertransistor (78), wodurch die Kapazität verringert wird, die durch die Produktterm-Signalleitung (PT) dargestellt wird.

2. Vorrichtung nach Anspruch 1, die eine Einrichtung aufweist, um während einer Leseoperation den Programmiertransistor (78) zu allen Zeiten einzuschalten, die Versorgungsspannung (PTG) mit der Erde bzw. Masse zu verbinden und den Auswahltransistor (74) in Antwort auf eine Hochspannung einzuschalten, die an seinen Auswahl-Steuereingang (ROW) angelegt wird, wodurch, wenn der Auswahltransistor (74) eingeschaltet wird, die Produktterm-Signalleitung (PT) mit der Erde bzw. der Masse verbunden wird, falls der Floating-Gate-Transistor (66) durch das Floating-Gate so gesteuert wird, daß er EIN ist, und ansonsten die Produktterm-Signalleitung (PT) nicht mit der Masse über den Floating-Gate-Transistor verbunden wird.

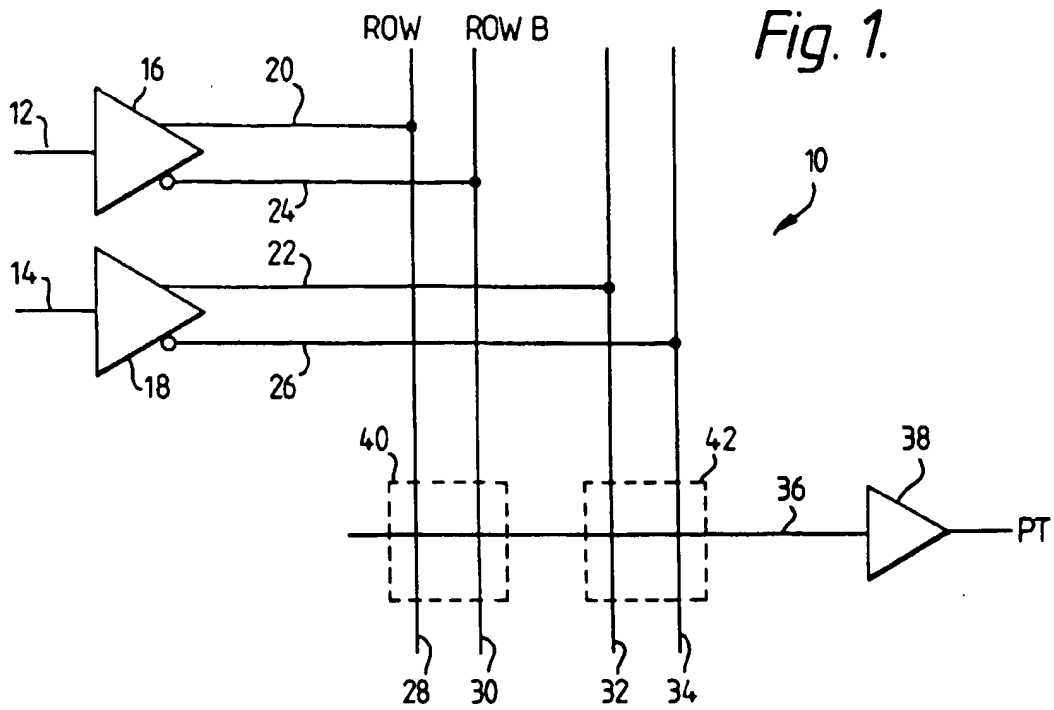
#### Revendications

1. Dispositif logique programmable comprenant un réseau ET/OU contenant des rangées de signaux d'entrée et des lignes de signaux de termes produits, dans lequel chaque connexion d'une rangée et d'une ligne de signal de terme produit contient un élément de commutation, cet élément de commutation comprenant :

un transistor de sélection (74) ayant une borne de source/drain connectée à une ligne de signal de terme produit (PT) et ayant une borne de commande pour recevoir une entrée de commande de sélection sur une rangée de si-

gnal d'entrée (ROW) ;  
 un transistor à grille flottante (66) ayant une borne de source/drain connectée à une autre borne de source/drain du transistor de sélection (74), dans lequel le fonctionnement du transistor à grille flottante (66) est commandé par des charges stockées sur une grille flottante (70) par l'intermédiaire d'un oxyde de grille propre à laisser passer des charges par effet tunnel, et dans lequel la mise en conduction du transistor de sélection (74) en réponse à l'entrée de commande de sélection (ROW) amène la ligne de signal de terme produit (PT) à indiquer la présence ou l'absence de charges sur la grille flottante (70), d'où il résulte que l'élément de commutation est lu ; et  
 un transistor de programmation (78) ayant une borne de source/drain connectée à une autre borne de source/drain du transistor à grille flottante (66), ayant une autre borne de source/drain connectée à une tension d'alimentation (PTG) et ayant une borne de commande pour recevoir une entrée de commande de programmation (DECA), dans lequel les charges stockées sur la grille flottante (70) sont fournies à partir de la tension d'alimentation (PTG) par l'intermédiaire du transistor de programmation (78) ; dans lequel le transistor de programmation est adapté à recevoir des tensions de programmation supérieures à une tension de fonctionnement normal ; et dans lequel le transistor de sélection (74) est physiquement plus petit que le transistor de programmation (78), réduisant ainsi la capacité présentée à la ligne de signal de terme produit (PT).

2. Dispositif selon la revendication 1, comprenant en outre des moyens pour, pendant une opération de lecture, commuter le transistor de programmation (78) à l'état passant à tout instant, connecter la tension d'alimentation (PTG) à la masse et commuter le transistor de sélection (74) à l'état passant en réponse à une tension haute appliquée à son entrée de commande de sélection (ROW), d'où il résulte que, quand le transistor de sélection (74) est commuté à l'état passant, la ligne de signal de terme produit (PT) est connectée à la masse si le transistor à grille flottante (66) est commandé pour être à l'état passant par la grille flottante, et la ligne de signal de terme produit (PT) n'est pas connectée à la masse par l'intermédiaire du transistor à grille flottante dans les autres cas.



*Fig. 2. (PRIOR ART)*

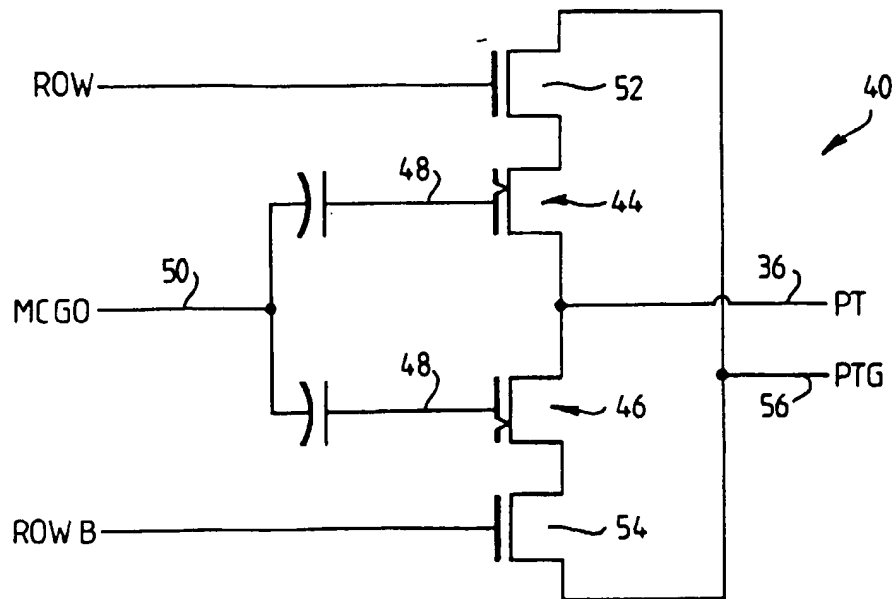




Fig. 3. (PRIOR ART)

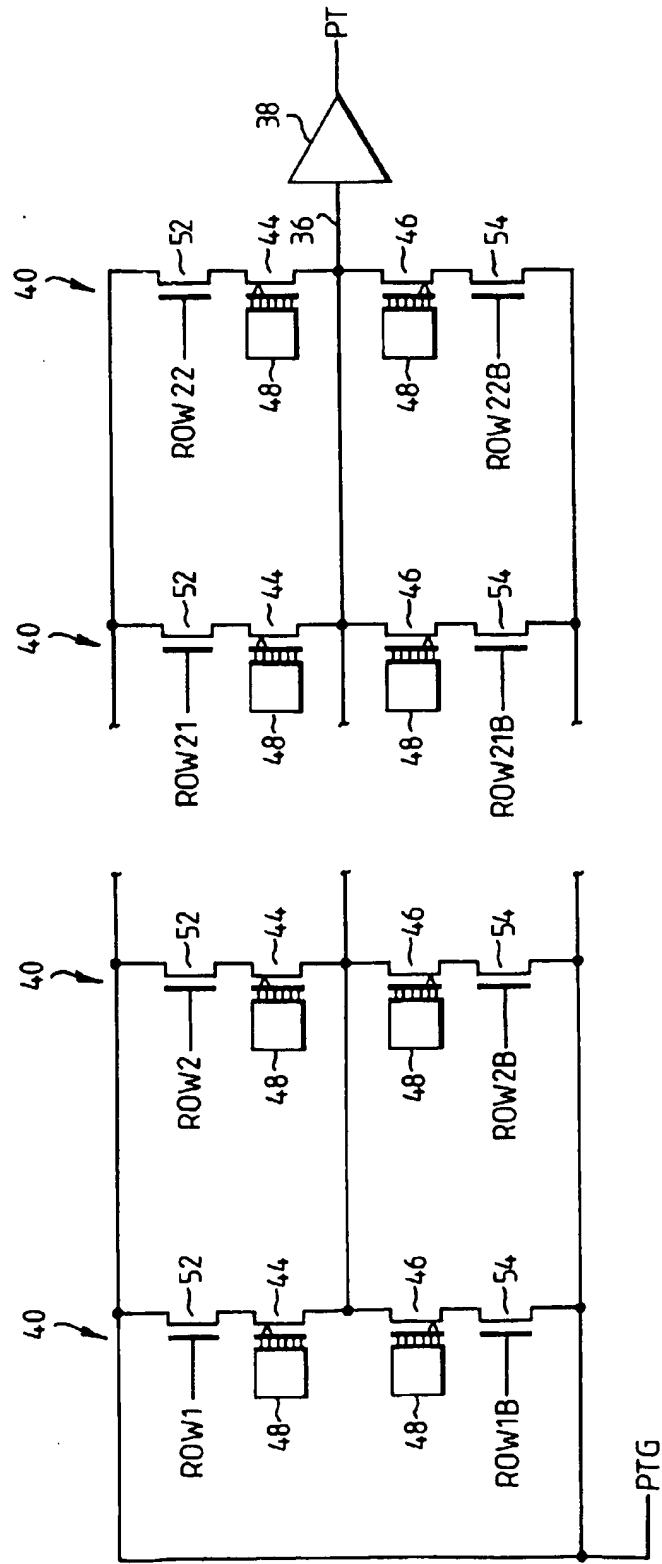


Fig. 4.

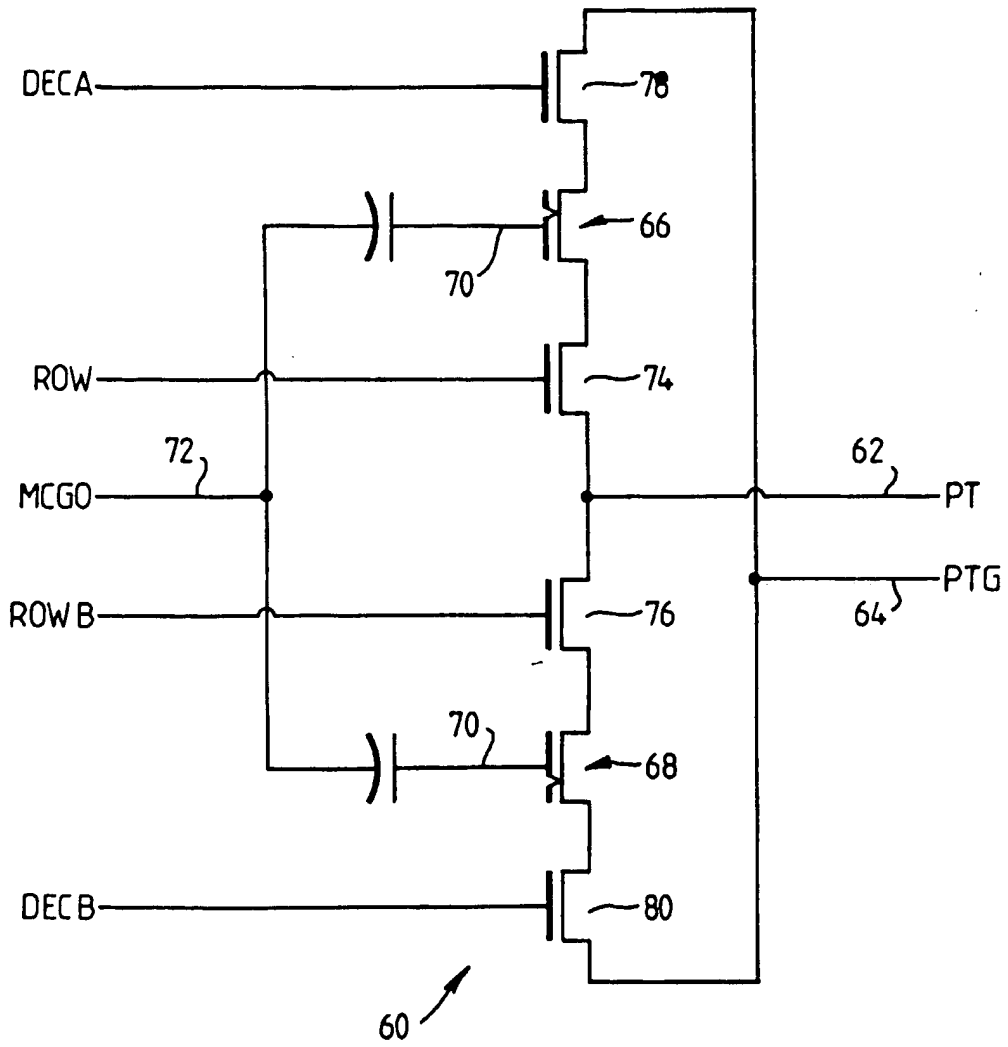


Fig. 5.

